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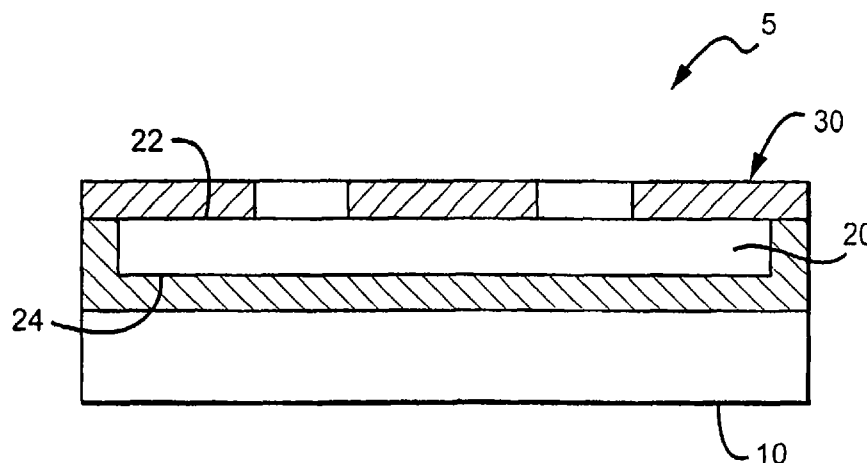
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(57) Abstract: Compositions and methods are provided whereby printed wiring boards (5) may be produced that comprise a) a substrate layer (10), and b) a hollow (20), mirror-clad optical wave-guide laminated onto the substrate layer (10). The printed wiring board (5) further comprises a cover material (30) coupled to the wave-guide (20).

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